

# Space Radiation and Plasma Environment Monitoring Workshop

Space Radiation & Plasma Environment Monitoring  
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## Highly Miniaturised Radiation Monitor (HMRRM)

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# HMRM Final Presentation

## Overview

- Key Requirements
- HMRM Design overview
- Particle Identification Algorithm
- Data products
- Detailed design overview
  - Mechanical
  - Electrical
- Programme status
- Future work

# HMRM Consortium

Consortium Member	Role
STFC - RAL Space	<ul style="list-style-type: none"><li>• HMRM Consortium Lead</li><li>• Overall design and development of HMRM</li></ul>
STFC – Technology Department	<ul style="list-style-type: none"><li>• HMRM ASIC Sensor Design and Development</li></ul>
Imperial College London – High Energy Physics	<ul style="list-style-type: none"><li>• HMRM Particle radiation simulation</li><li>• HMRM Particle Identification algorithm development</li><li>• HMRM testing</li></ul>
ESA ESTEC	<ul style="list-style-type: none"><li>• Technical contract management</li></ul>

## Consortium strengths:

- Expertise in development of Space instrumentation
- Expertise in instrumentation for High Energy Physics instrumentation
- Knowledge of the space radiation environment

# Aims of the HMRRM programme

Develop a “chip sized” <sup>1</sup> prototype radiation monitor suitable for application in:

- Coarse radiation housekeeping
- Alert and saving function
- Support to platform and payload systems

Note 1: The clear implication of “chip sized” is that the HMRRM is to be smaller, lighter and consume less power than a more conventional radiation monitor...

# ***HMRM***

## ***Key Requirements***

# Key Requirements:

## Functional Requirements

### Requirement

The highly miniaturized radiation monitor (HMRM) shall be an ASIC/APS radiation detector with on-chip sensor elements, read-out electronics, power and communications resources

The HMRM design shall minimize the number of external components needed to operate the device.

Preferred process for the CMOS die shall be a commercial process by a European Foundry

The HMRM design shall minimize the number of pins needed to interface the spacecraft/host PCB

Dosimeter function: The HMRM shall maintain a counter of the accumulated total dose detected

# Key Requirements:

## Functional Requirements (cont.)

### Requirement

Particle Rate Meter function: a rate meter counter shall be maintained. The maximum particle rate shall be  $10^7$  (#/cm<sup>2</sup>/sec) or higher

Particle Species Identification function: capability to classify on chip detected events with respect to particle species (electrons, protons, ions) shall be implemented

The dynamic range shall be such to maximize the discrimination of different particles species for typical satellite orbits within the energy range as indicated in the Statement of Work

The highly miniaturized radiation monitor shall have a temperature monitor on chip. The temperature sensor shall have an accuracy of better than 1°C over the range -40 to +80°C. All calibration parameters to be provided with the detector

# Key Requirements :

## Functional Requirements (cont.)

### Requirement

An in-flight calibration procedure shall be implemented in order to check sensor drift

The HMRM shall include the ability to isolate erroneous sensor elements

The HMRM design shall foresee the possibility of coinciding operation modes in which several HMRM devices are distributed on different location of the spacecraft



# Key Requirements:

## Physical and Electrical Requirements

### Requirement

The package selected shall allow the possibility to stack more than one detector and to interleave detector chips with passive shielding materials

The power dissipation shall be minimized and be less than 200mW on average

The radiation sensor shall require a minimum of power supply pins. The power supply voltage shall be 5.0 V or lower

HMRM shall be tolerant to ESD on any of its pins with a Human Body Model voltage of at least 300V

The HMRM shall require a minimum of external reference voltages

The mass of HMRM device shall be less than 20 g

# Key Requirements:

## Environmental Requirements

### Requirement

The radiation detector single chip shall have a radiation TID tolerance of at least 100kRad

The radiation detector single chip shall be latch up free

The radiation detector single chip shall have an operating temperature range of -40 to +80°C

The radiation detector single chip shall have a storage temperature range of -60 to +125°C

The sensor shall be capable of meeting the performance requirements under full solar illumination at an orbital radius of 1 AU

# Key Requirements:

## Quality and Test Requirements

### Requirement

Evaluation testing shall be performed compliant to ECSS 9020 [ AD-2]

Testing shall be performed to find the 50% failure level of the detector to at least the following conditions:

- Mechanical Shock level
- Mechanical Vibration level (random and sine)
- High and Low Temperature
- Radiation total dose

The HMRRM shall be free of all non-European export restrictions and shall take all measures needed to ensure this

# Key Requirements: Summary and interpretation

## Customer needs:

- High quality characterisation of the space radiation environment
  - Dose
  - Electron and proton spectra
  - Wide range of environments
- Low cost
  - Unit cost of Monitor
  - Spacecraft resources (power, mass, TM etc.)
  - Integration
  - Data processing

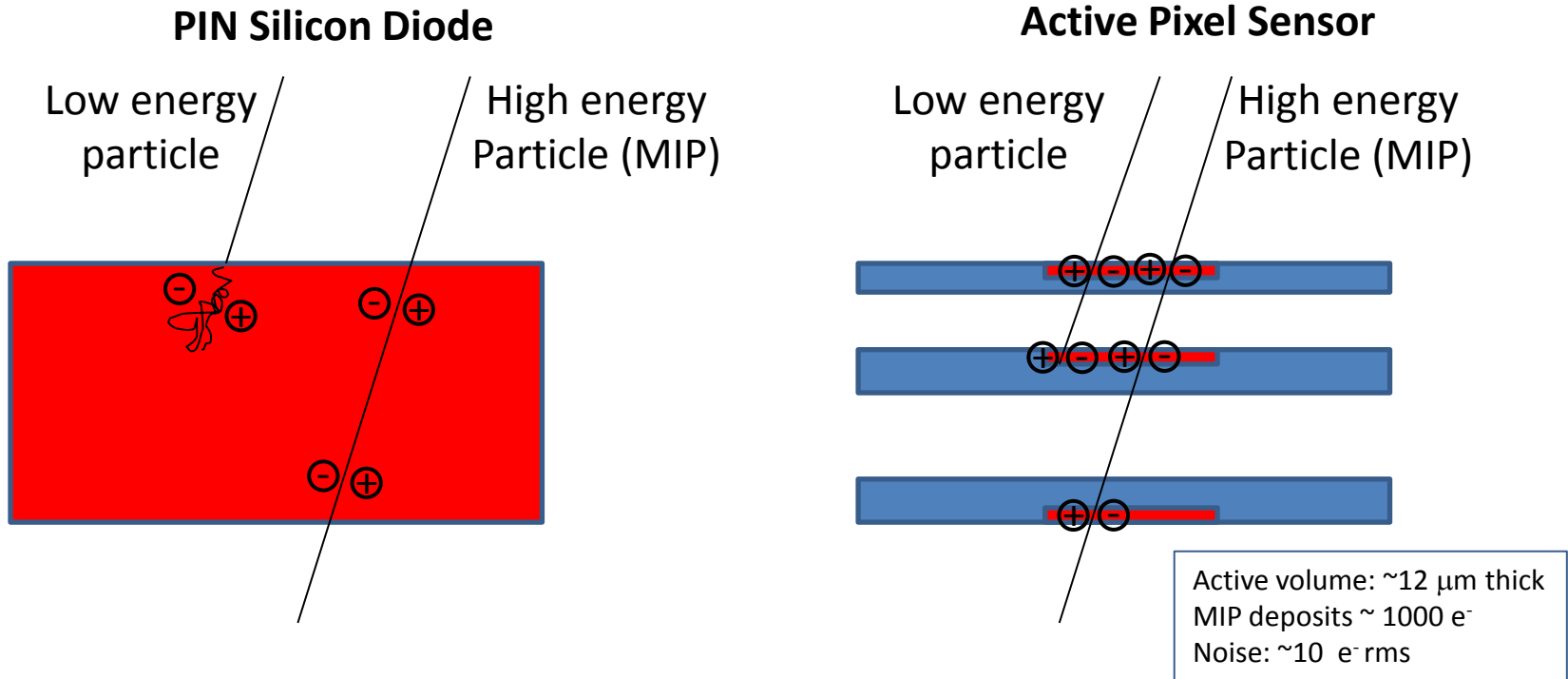
# ***HMRM Design overview***

# Sensor Tradeoff

- Key tradeoff in the architecture of the sensing element of the HMRRM was between a PIN Silicon Diode and Active Pixel Sensors
- APS sensors have several advantages for application in the HMRRM

Parameter	Comments
Mass	Integrating the detector function with the signal readout makes APS much more compact
Sensor integration	The sensing element is fully integrated on the monitor chip with APS sensors
Signal quality	Able to achieve $\sim 10 e^-$ rms noise with saturation of $15 ke^-$ with APS
Power supply	Bias voltage of CMOS is 3.3 V and no need for “high” voltages to drive the diode into depletion
Flux dynamic range	The APS is able to be electronically shuttered to avoid pileup in high flux environments
Bremsstrahlung susceptibility	The APS detectors have a low cross section for interaction with high energy photons

# Sensor Tradeoff



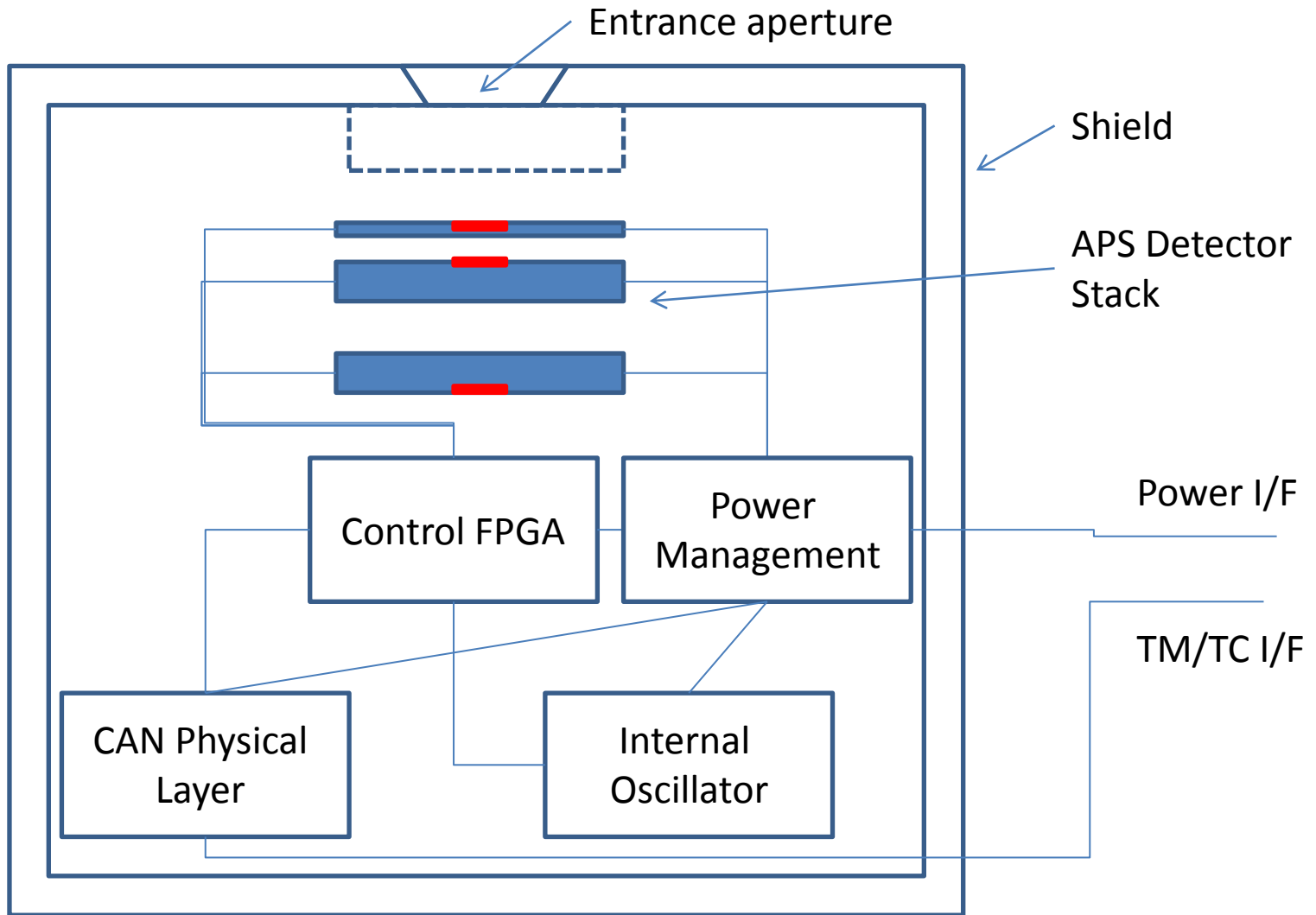
- Ambiguity exists where the energy deposited in the detector by a low energy particle is the same as the energy deposited by a MIP passing through the detector
- Active volume of APS detector: 12  $\mu\text{m}$  with 50-500  $\mu\text{m}$  substrate
- Active volume of Silicon diode: > 50  $\mu\text{m}$
- With APS sensors; judicious selection of Silicon substrate thickness allows the  $dE/dx$  curve to be sampled and uniquely identify the particle species and energy

# HMRM Design Summary

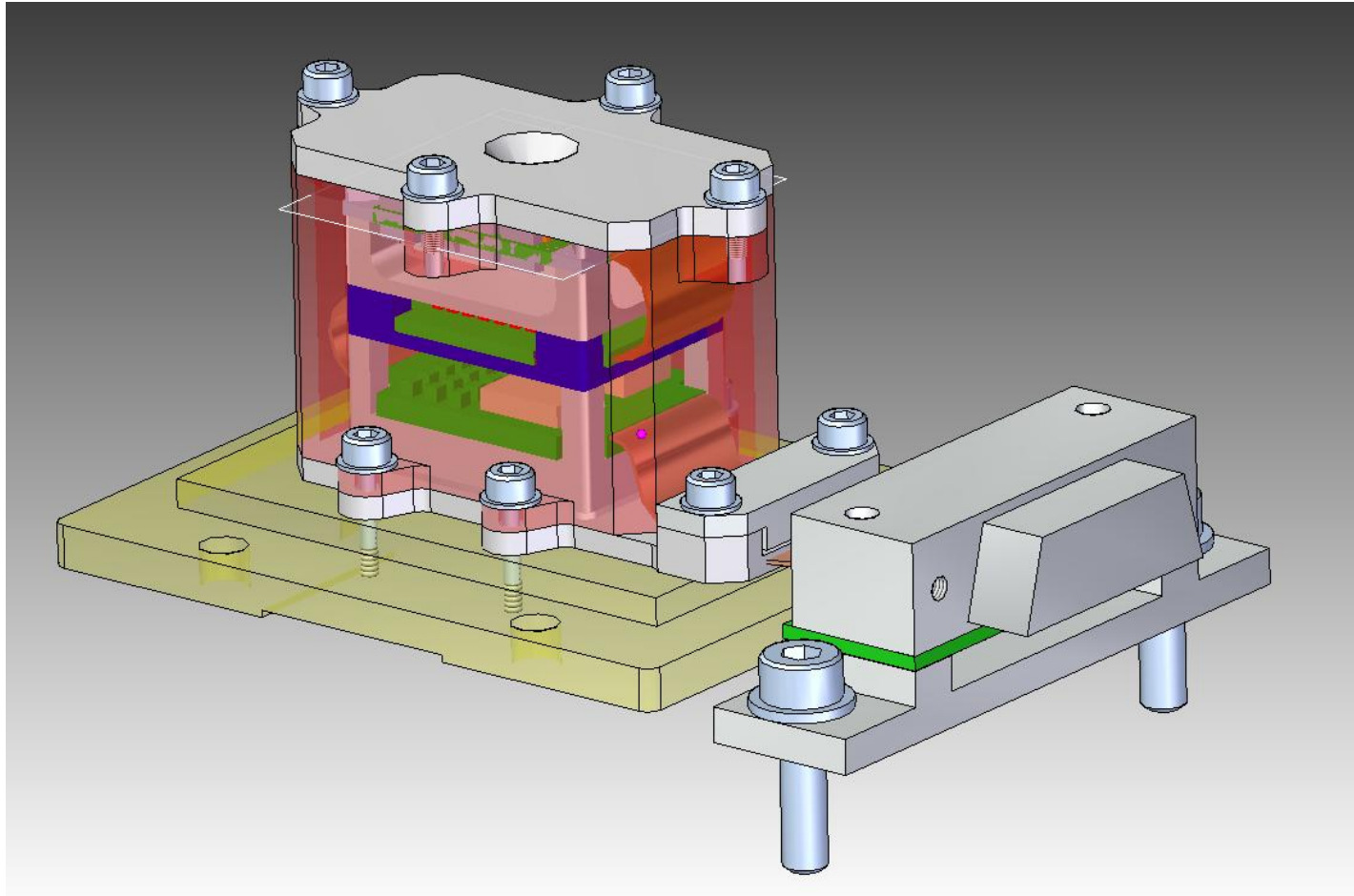
Characteristic	Specification	
Sensing element	50 x 50 array of 20 $\mu\text{m}$ x 20 $\mu\text{m}$ , 4T APS detectors	
Configuration	Either single chip, or integrated monitor	
Mass	Integrated monitor: 52g (including fasteners and connector) in a stack configuration	Single Chip: 0.8 g
Power	1-2 W (TBC) depending of number of detectors in stack and architecture of power supply	Single Chip: < 200 mW per ASIC
Volume	Integrated monitor: 20x25x30mm - 15 cc	Single chip (unpackaged): 2.54x10x0.6 mm
Radiation measurements	Integrated Monitor: Dose Dose rate Particle radiation spectra: <ul style="list-style-type: none"> <li>• Electrons: 0.06 – 6 MeV</li> <li>• Protons: 1 – 500 MeV</li> </ul>	Single Chip: Dose Dose rate
Maximum flux	$10^8 \text{ \#/cm}^2/\text{s}$	
Aux. measurement	Temperature	
Interface	Integrated Monitor: Data: TM/TC CCSDS CAN Power: 5 V (standard)	Single Chip: Data: CMOS logic I/O Power: 3.3 V + 0.3V references



# HMRM Block Diagram



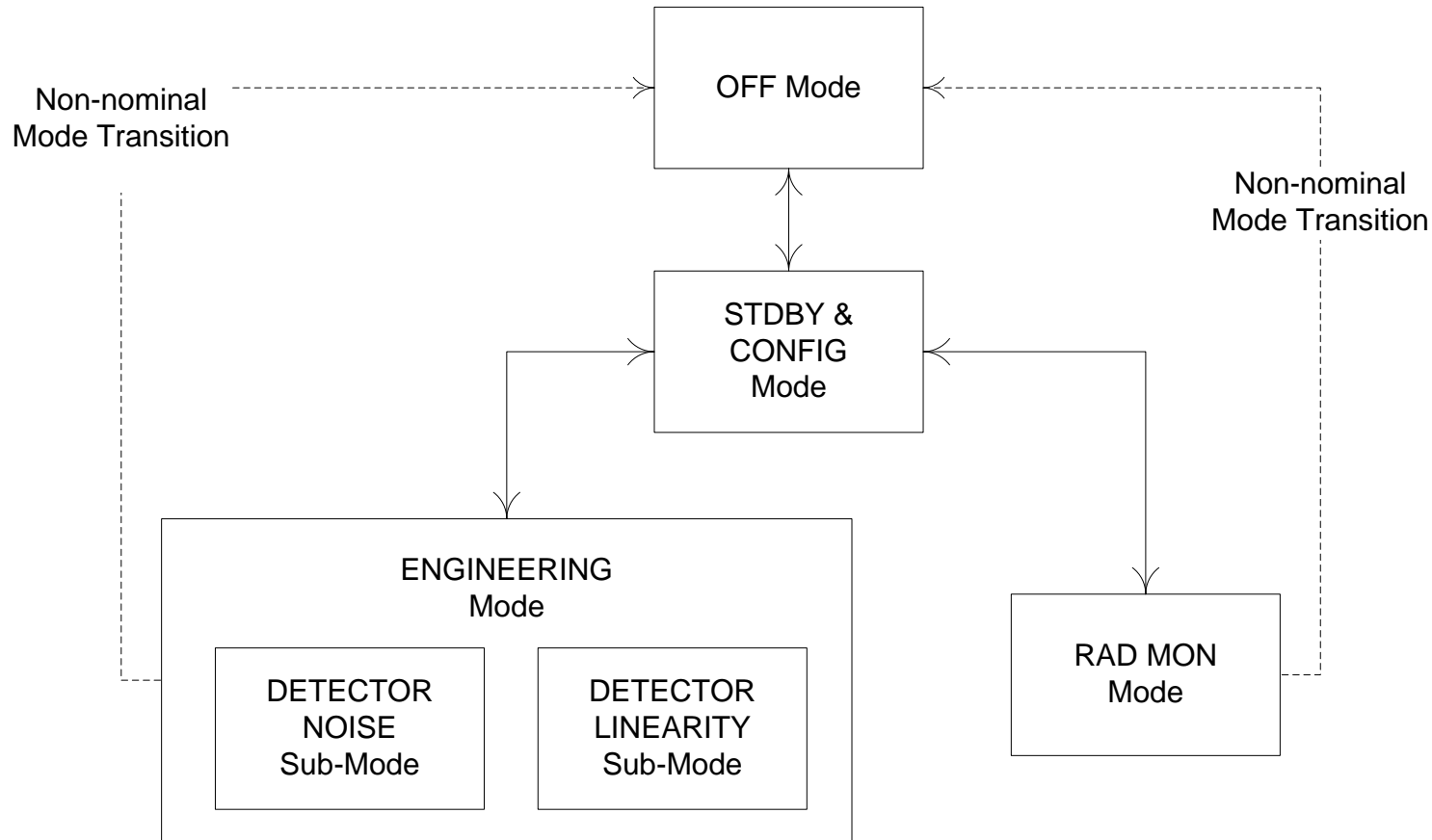
# HMRM CAD Model



# HMRM Structure



# HMRM Mode Transition Diagram



# ***HMRM***

## ***Data products***

# Data Products

- HMIRM Generates four types of CCSDS compliant TM frames
  - Engineering
    - Basic radiation HK data
  - “Full Science”
    - Provides data for retrieval of particle spectra
  - Transparent
    - Diagnostic
  - Error frames



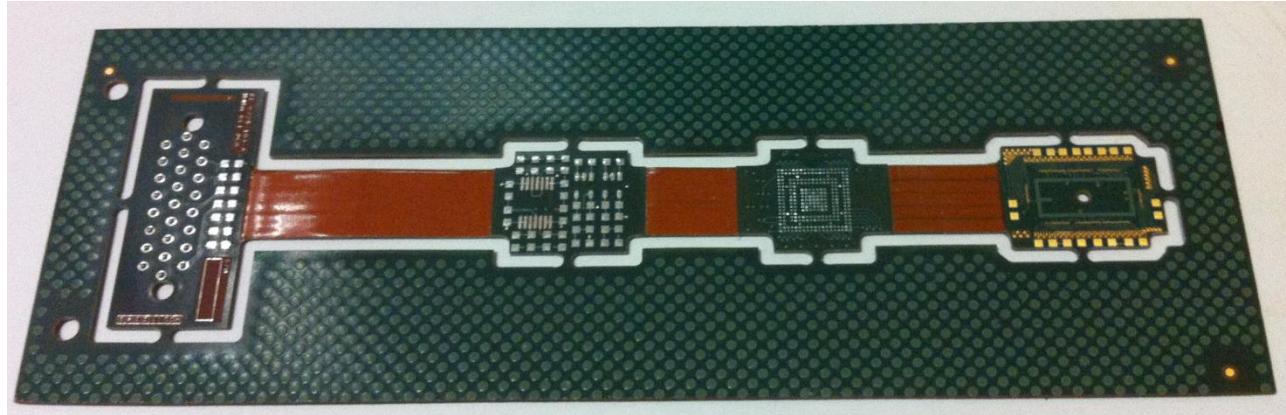
# Data Products

- Engineering and “Full Science” frames are generated at a user configurable rate
- TM bandwidth a function of cadence of measurements only
  - In normal operation average TM rate can be exceedingly low
- Transparent generated at maximum capacity of CAN bus



# PCB

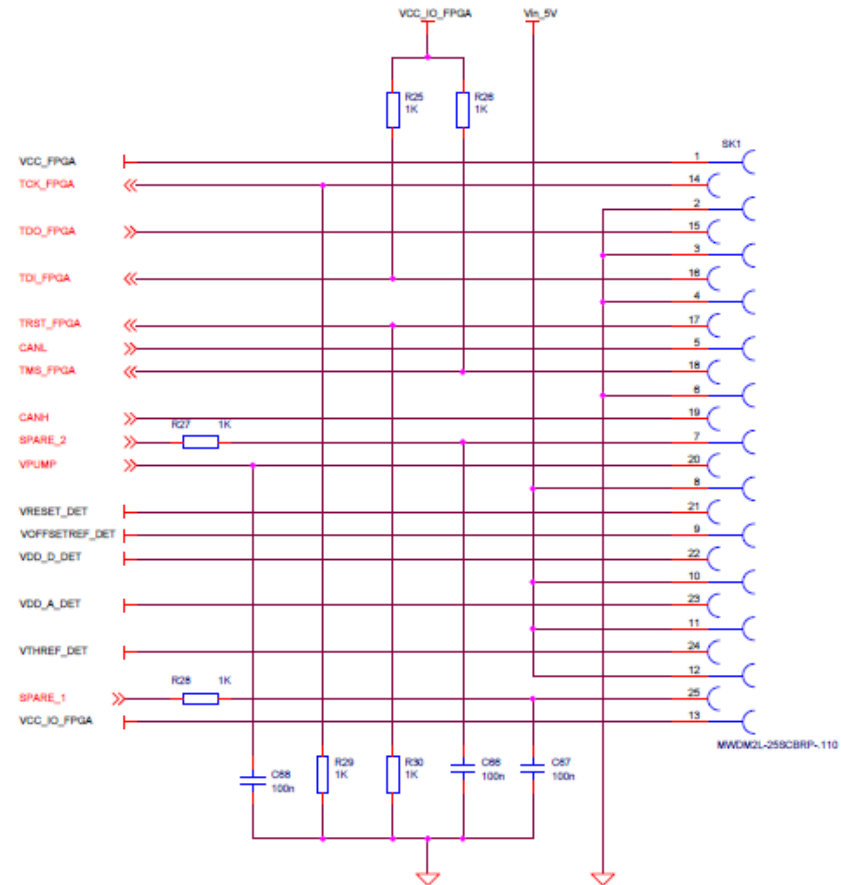
- Flex rigid PCB design
- Four rigid boards
  - Interface connector PCB
  - Interface PCB
  - FPGA PCB
  - Detector PCB



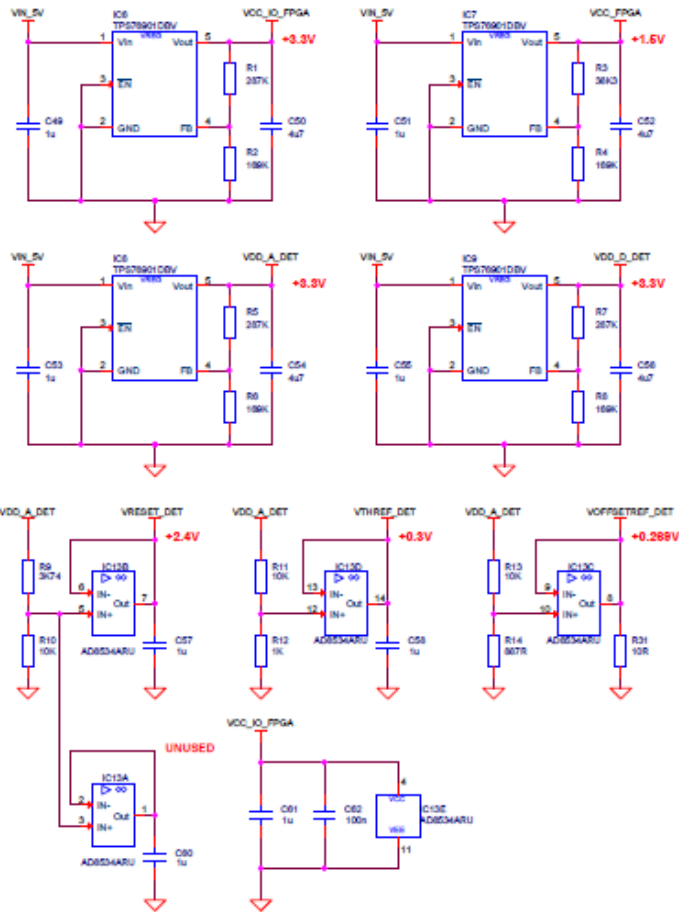
- Very complex design challenge
  - 10 layer PCB
  - 248 through holes
  - 100 buried vias
  - 151 micro-vias
  - HASL finish for soldered components
  - Gold finish for wire bonded ASICs

# Interface connector

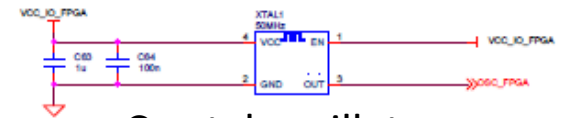
- 25-way MDM
- Power +5V / return
- CAN I/F lines
- Tell back
- Extra functions for Phase A/B device
  - voltage probes
  - JTAG for FPGA re-programming



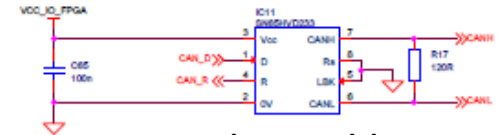
# Interface PCB



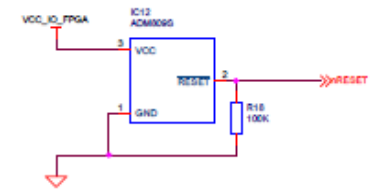
Reference voltages



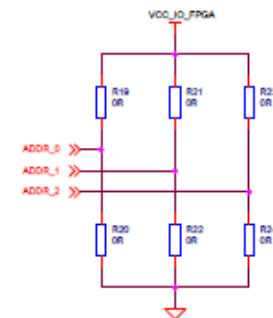
Crystal oscillator



CAN Physical layer IC

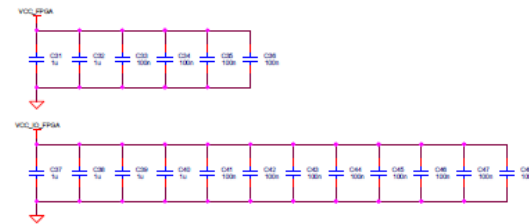
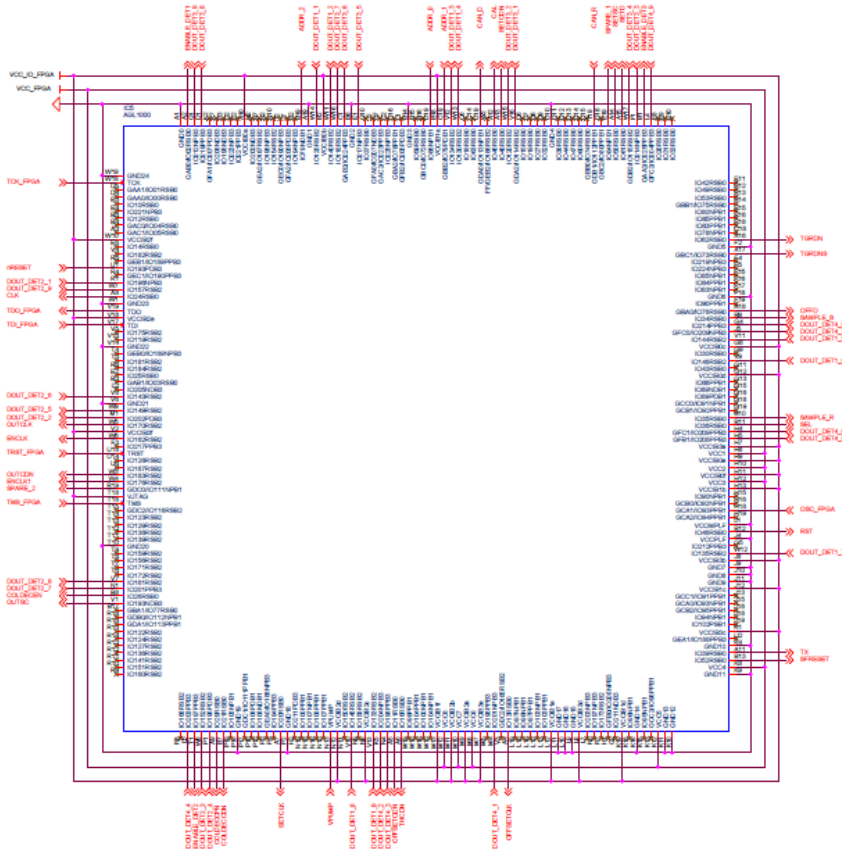


FPGA Power up / reset



Ground point

# FPGA Board



- 281 contacts
- 10x10 mm package
- Low proportion of programmable I/Os utilised
- High density micro vias and buried vias required to route signals to flex layers

# FPGA Functions

CAN (Controller Area Network) Hurricane Core  
Time keeping  
Command CODEC  
Telemetry packaging  
System clock  
Radiation monitoring data processing  
APS configuration register programming logic  
APS waveform generation  
Bad pixel masking function  
Engineering mode processing

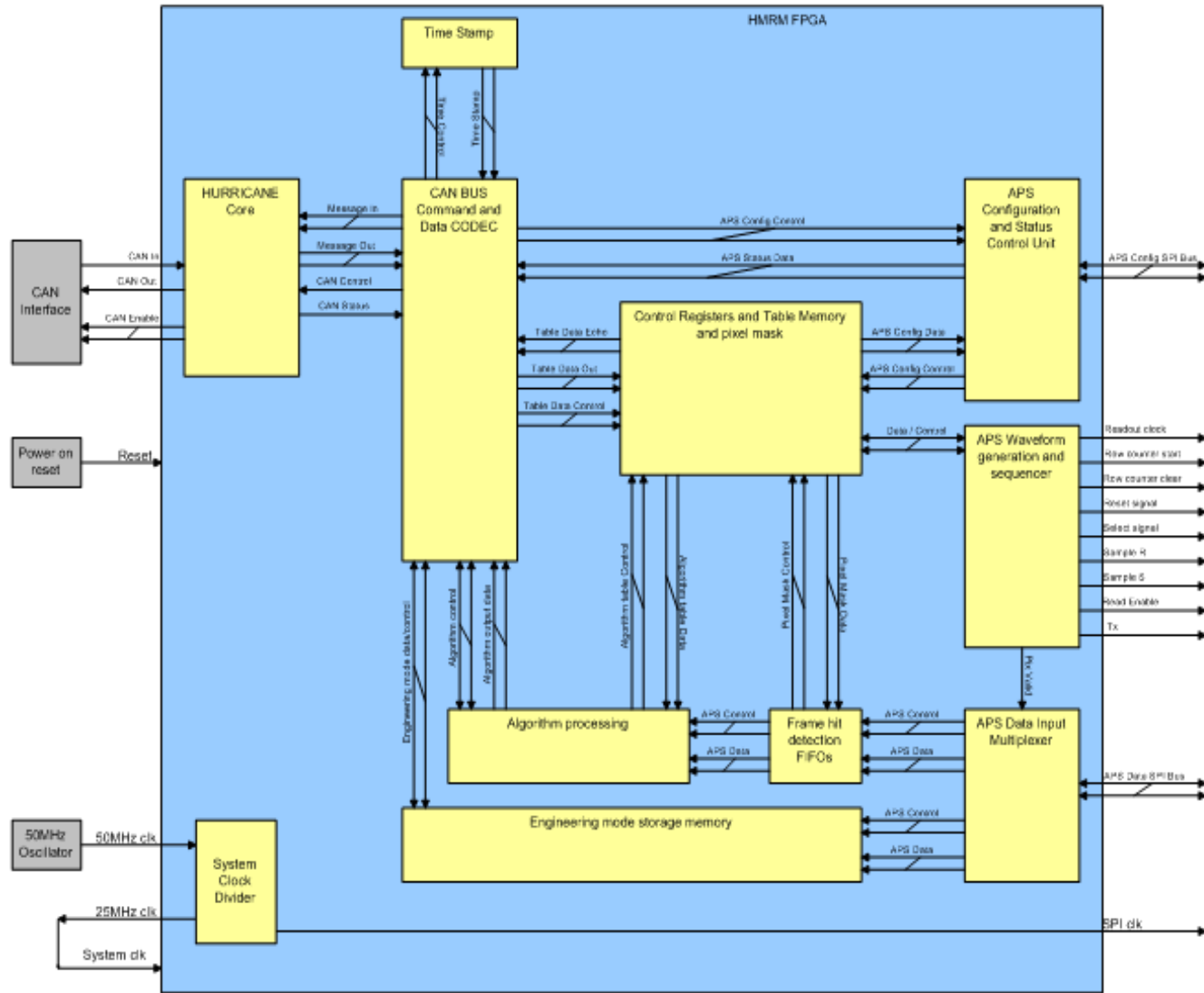
Device:  
Microsemi  
AGL 1000V - CSG281

COTS device  
Flash programmable  
1,000,000 System gates

~80% utilisation



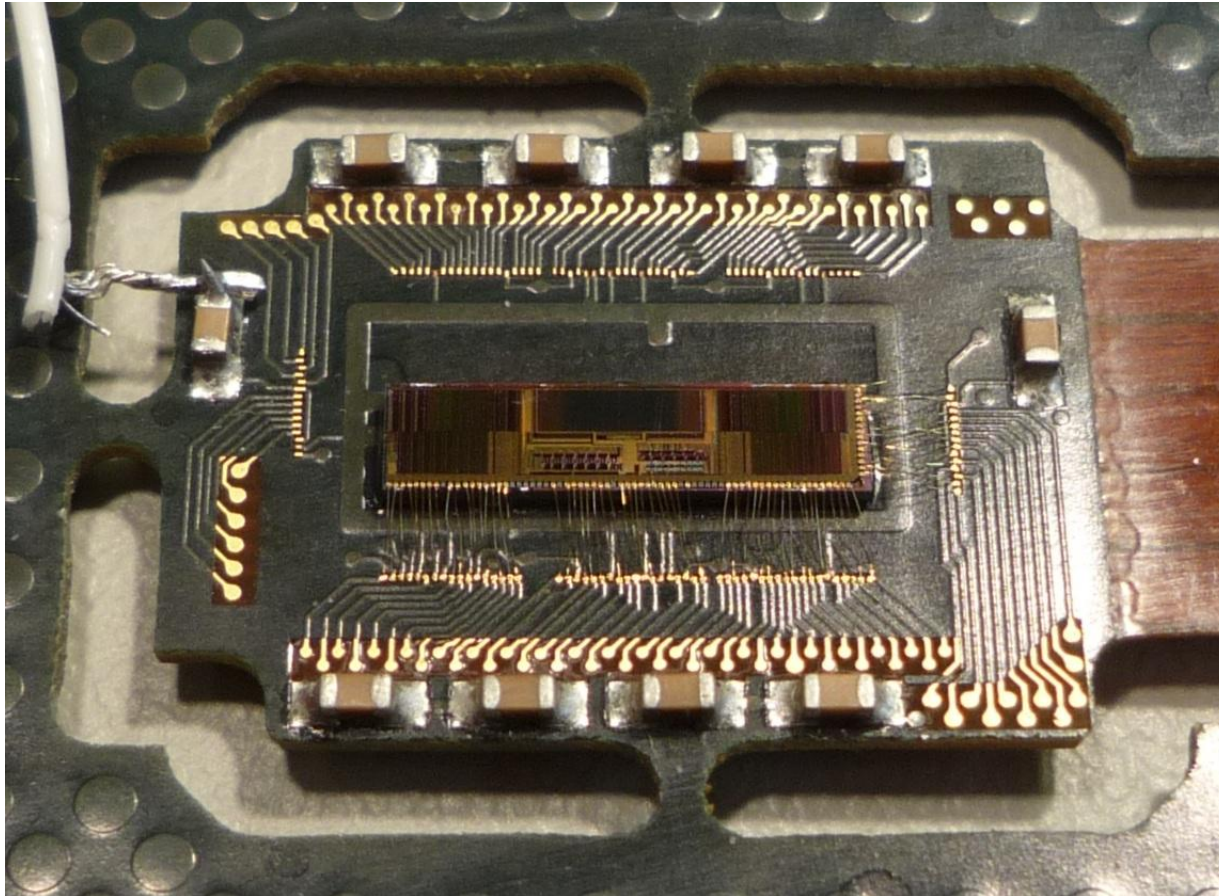
# FPGA Architecture





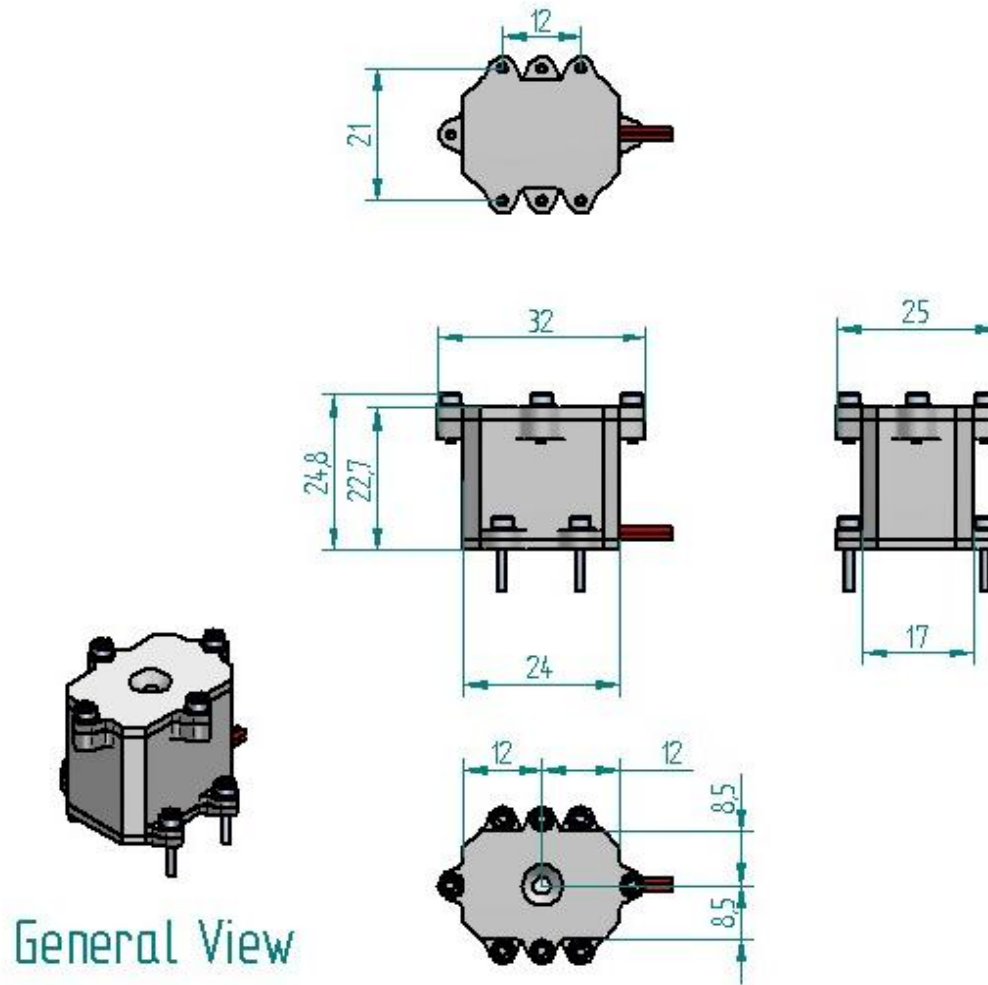


# Detector PCB

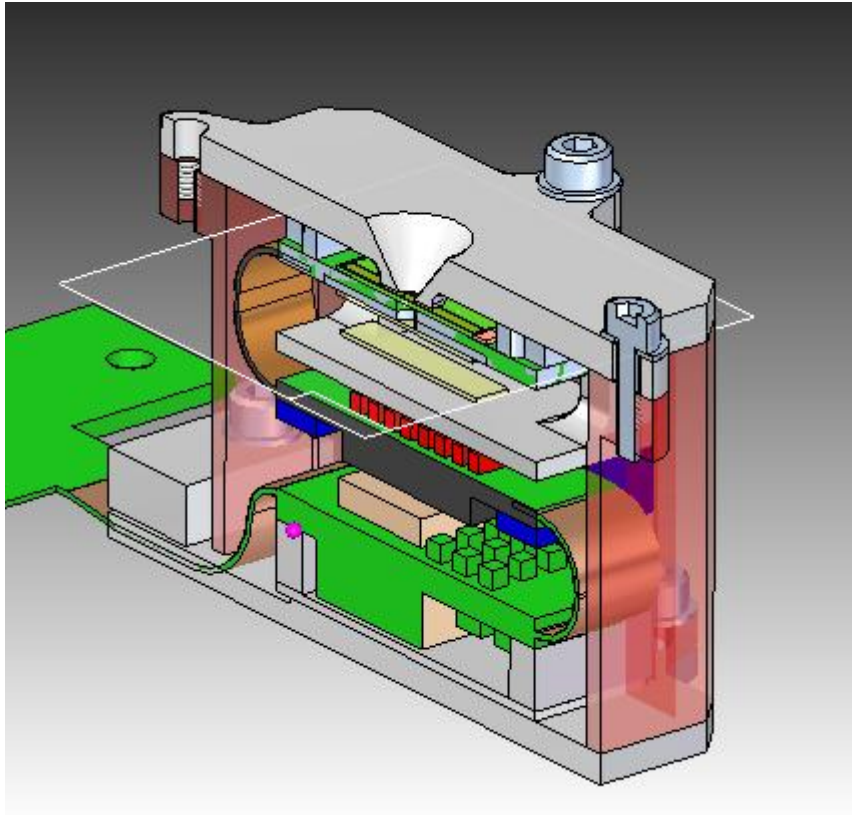




# Mechanical Design



# Mechanical Design



Three main mechanical elements of the HMRM Chassis

- Lid
  - Provides the prescribed geometry for detector telescope
  - Mounts the window (for visible blindness)
- Body
  - Main structural housing around electronics and sensing elements
- Base
  - structural interface to spacecraft
  - shields back of HMRM

Fabricated in Titanium

Mass 52g (including fasteners and connector)

# ***HMRM Programme Status***

# HMRM Programme Status

- Design of Phase A/B monitor complete
- ASIC run #2 to be submitted today!
  - Returned from foundry ~ Sep. 2012
- Wafer level checkout, screening and characterisation
- Assembly into deliverable monitors
- Test and characterisation

# *HMRM Future Work*

# Future work

- Complete the hardware technology demonstration aspects of the HMRRM programme with the second iteration of the ASIC
  - ASIC functional and performance testing
  - Integration of ASICs into a HMRRM monitor
  - HMRRM functional, performance and environmental testing
- Commercialisation
  - The Statement of Work explicitly calls for planning for commercialisation of the HMRRM
  - The next steps in this regard include:
    - Baselining the differences between the Phase A/B device and a flight qualifiable Phase C/D device
    - Completion of the planning of the development programme to develop the HMRRM to this level of maturity

# Summary

- The HMRRM Phase A/B programme is close to successfully demonstrating the remarkable potential of applying CMOS APS technology to the design of a highly miniaturised spacecraft radiation monitor
- The presenters acknowledges the contribution of ESA to this work in the awarding of AO/1-5978/09/NL/AT to the consortium and the invaluable assistance from ESTEC staff